

September 2014

FCP170N60

N-Channel SuperFET® II MOSFET

600 V, 22 A, 170 mΩ

Features

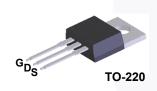
- 650 V @T_J = 150°C
- Typ. $R_{DS(on)}$ = 150 m Ω
- Ultra Low Gate Charge (Typ. Q_g = 42 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 190 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

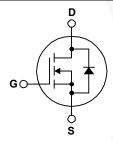
Applications

- · Telecom / Sever Power Supplies
- · Industrial Power Supplies
- · AC-DC Power Supply

Description

SuperFET[®] II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCP170N60	Unit	
V _{DSS}	Drain to Source Voltage			600	V	
	Cata ta Causaa Valta aa	- DC		±20	V	
V_{GSS}	Gate to Source Voltage	- AC		±30	V	
	Drain Current	- Continuous (T _C = 25°C)		22		
D Drain Current	- Continuous (T _C = 100°C)		14	_ A		
I _{DM}	Drain Current	- Pulsed	- Pulsed (Note 1)			
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		525	mJ		
I _{AR}	Avalanche Current (Note		(Note 1)	5	Α	
E _{AR}	Repetitive Avalanche Energy (N		(Note 1)	2.27	mJ	
dv/dt	MOSFET dv/dt		(Note 3)	100	V/ns	
αν/αι	Peak Diode Recovery dv/dt			20	V/IIS	
П	Dower Discipation	(T _C = 25°C)		227	W	
P_{D}	Power Dissipation	- Derate above 25°C		1.82	W/°C	
T _J , T _{STG}	Operating and Storage Tempe	erature Range		-55 to +150	οС	
T _L	Maximum Lead Temperature 1/8" from Case for 5 Seconds	300	°C			

Thermal Characteristics

Symbol	Parameter FCP170N60			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max. 0.55			
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. 40			

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP170N60	FCP170N60	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}, T_J = 25^{\circ}\text{C}$	600	-	-	V
	Drain to Source Breakdown Voltage	$I_D = 10 \text{ mA,V}_{GS} = 0 \text{ V, T}_J = 150^{\circ}\text{C}$	650	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.67	-	V/°C
ı	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	μА
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	1.2	-	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 11 A	-	150	170	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 11 A	-	17	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 380 V, V _{GS} = 0 V f = 1 MHz		2150	2860	pF
C _{oss}	Output Capacitance			60	80	pF
C _{rss}	Reverse Transfer Capacitance			2.65	-	pF
Coss (eff.)	Effective Output Capacitance	$V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$	- \	190	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 11 A,	- \	42	55	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	9	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	11	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.95	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	21	50	ns
t _r	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_{D} = 11 \text{ A},$		- /	12	35	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$		-/	55	120	ns
t _f	Turn-Off Fall Time		(Note 4)	-	3.8	18	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	22	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	66	Α
V_{SD}	Drain to Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{SD} = 11 \text{ A}$		-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 11 A,	-	346	-	ns
Q_{rr}	Reverse Recovery Charge dI _F /dt = 100 A/μs		-	6.2	-	μС

Notes:

- ${\it 1. Repetitive\ rating: pulse\ width\ limited\ by\ maximum\ junction\ temperature}$
- 2. I_{AS} = 5 A, R_{G} = 25 Ω , Starting T_{J} = 25°C
- 3. I $_{SD} \leq$ 11 A, di/dt \leq 200 A/ $\mu s,~V_{DD} \leq$ 380 V, Starting T $_{J}$ = 25°C
- 4. Essentially independent of operating temperature typical characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

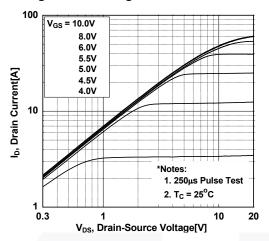


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

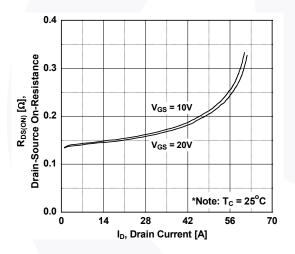


Figure 5. Capacitance Characteristics

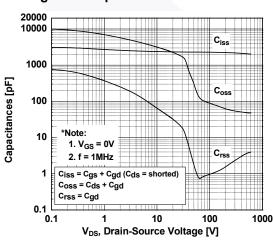


Figure 2. Transfer Characteristics

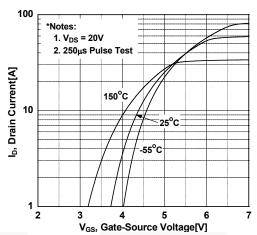


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

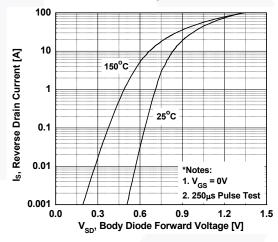
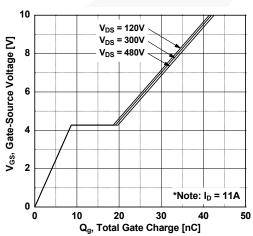


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

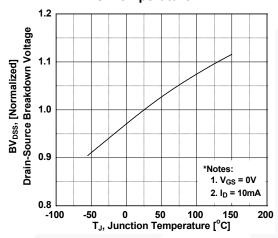


Figure 9. Maximum Safe Operating Area

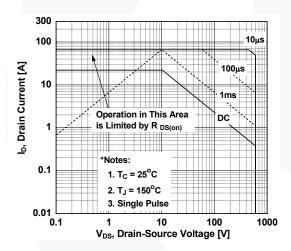


Figure 11. Eoss vs. Drain to Source Voltage

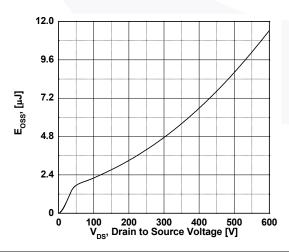


Figure 8. On-Resistance Variation vs. Temperature

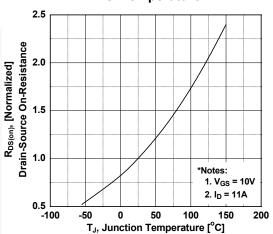
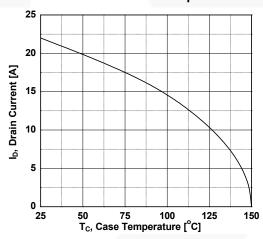
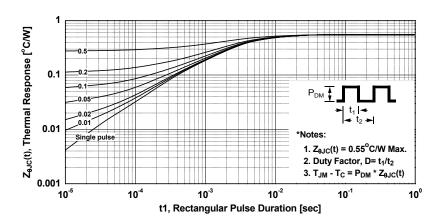


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



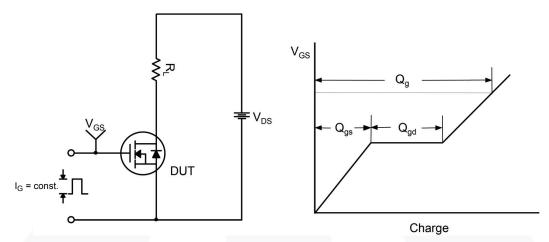


Figure 13. Gate Charge Test Circuit & Waveform

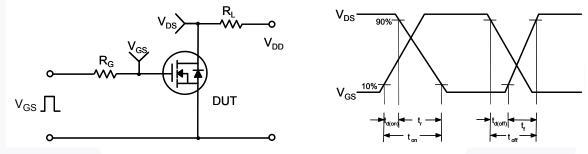


Figure 14. Resistive Switching Test Circuit & Waveforms

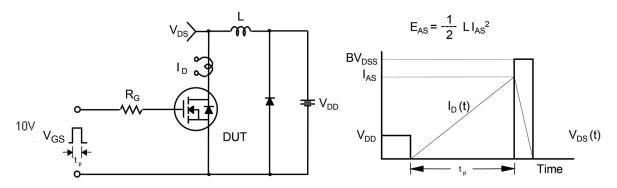


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

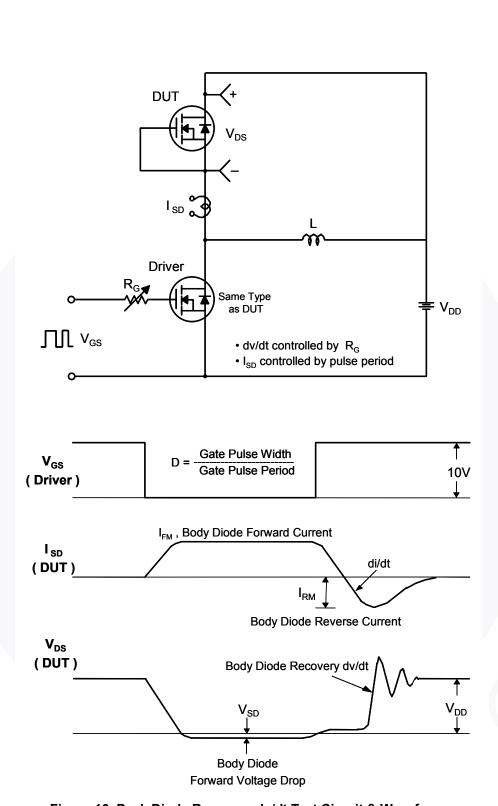
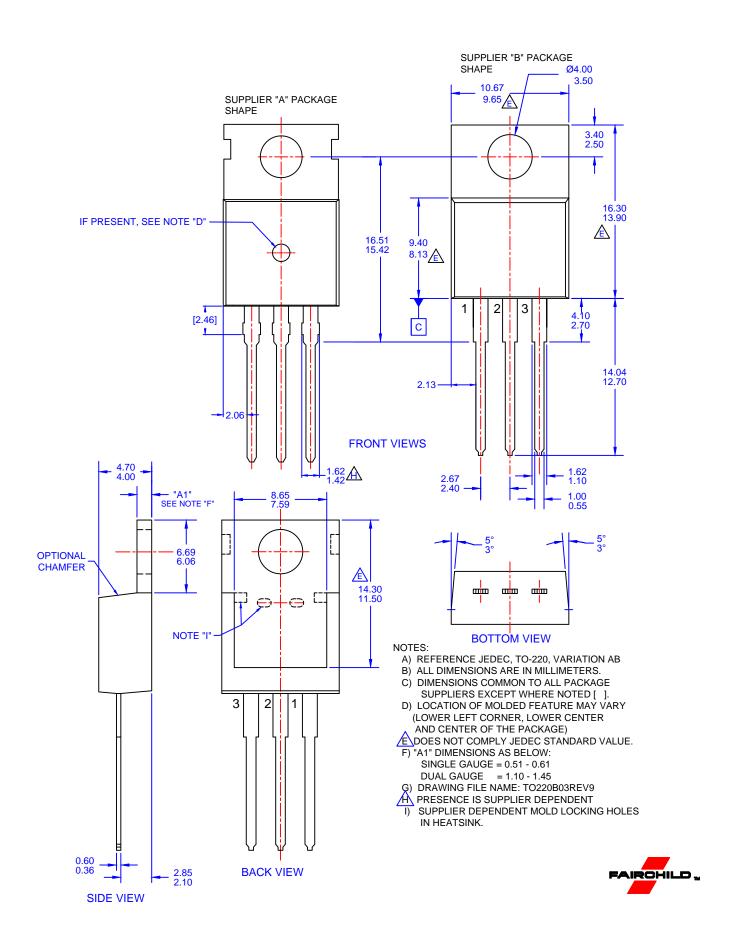


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms







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Definition of Terms				
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